

Andrew A Shapiro

List of Publications by Year in descending order

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49
papers

2,888
citations

361413

20
h-index

345221

36
g-index

49
all docs

49
docs citations

49
times ranked

2493
citing authors

#	ARTICLE	IF	CITATIONS
1	Advances in additive manufacturing of metal-based functionally graded materials. <i>International Materials Reviews</i> , 2021, 66, 1-29.	19.3	169
2	Integration of Processing and Microstructure Models for Non-Equilibrium Solidification in Additive Manufacturing. <i>Metals</i> , 2021, 11, 570.	2.3	15
3	Fabrication defects and limitations of AlSi10Mg lattice structures manufactured by selective laser melting. <i>Proceedings of the Institution of Mechanical Engineers, Part L: Journal of Materials: Design and Applications</i> , 2021, 235, 2071-2082.	1.1	3
4	Analysis of formation and growth of the β phase in additively manufactured functionally graded materials. <i>Journal of Alloys and Compounds</i> , 2020, 814, 151729.	5.5	28
5	Characterization of a functionally graded material of Ti-6Al-4V to 304L stainless steel with an intermediate V section. <i>Journal of Alloys and Compounds</i> , 2018, 742, 1031-1036.	5.5	89
6	Experimental analysis and thermodynamic calculations of an additively manufactured functionally graded material of V to Invar 36. <i>Journal of Materials Research</i> , 2018, 33, 1642-1649.	2.6	20
7	Additive manufacturing of a functionally graded material from Ti-6Al-4V to Invar: Experimental characterization and thermodynamic calculations. <i>Acta Materialia</i> , 2017, 127, 133-142.	7.9	298
8	Additive Manufacturing for Aerospace Flight Applications. <i>Journal of Spacecraft and Rockets</i> , 2016, 53, 952-959.	1.9	105
9	Development and characterization of Ti-6Al-4V to 304L stainless steel gradient components fabricated with laser deposition additive manufacturing. <i>Materials and Design</i> , 2016, 104, 404-413.	7.0	201
10	Functionally graded material of 304L stainless steel and inconel 625 fabricated by directed energy deposition: Characterization and thermodynamic modeling. <i>Acta Materialia</i> , 2016, 108, 46-54.	7.9	432
11	Cryogenic in situ microcompression testing of Sn. <i>Acta Materialia</i> , 2014, 78, 56-64.	7.9	38
12	Developing Gradient Metal Alloys through Radial Deposition Additive Manufacturing. <i>Scientific Reports</i> , 2014, 4, 5357.	3.3	222
13	Technology Management. , 2014, , 599-618.		0
14	Thin and Thermally Stable Periodic Metastructures. <i>Experimental Mechanics</i> , 2013, 53, 1735-1742.	2.0	45
15	Integrating toxicity reduction strategies for materials and components into product design: A case study on utility meters. <i>Integrated Environmental Assessment and Management</i> , 2013, 9, 319-328.	2.9	2
16	A study of solder alloy ductility for cryogenic applications. , 2013, , .		10
17	In-Situ SEM Characterization of Fracture Behavior. <i>Microscopy and Microanalysis</i> , 2012, 18, 792-793.	0.4	1
18	Willingness to engage in a pro-environmental behavior: An analysis of e-waste recycling based on a national survey of U.S. households. <i>Resources, Conservation and Recycling</i> , 2012, 60, 49-63.	10.8	273

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19	Cryogenic Charpy impact testing of metallic glass matrix composites. Scripta Materialia, 2012, 66, 284-287.	5.2	40
20	Transition to Lead-Free Products in the US Electronics Industry: A Model of Environmental, Technical, and Economic Preferences. Environmental Modeling and Assessment, 2011, 16, 107-118.	2.2	6
21	A novel energy-based approach for merging finite elements. International Journal for Numerical Methods in Engineering, 2011, 85, 187-205.	2.8	0
22	Toxicity potential indicator analysis for alternatives recommendations in the RIO Tronics utility meter pulse products. , 2011, , .		0
23	Computational Evolutionary Embryogeny. IEEE Transactions on Evolutionary Computation, 2010, 14, 301-325.	10.0	13
24	Electronic Packaging Materials for Extreme, Low Temperature, Fatigue Environments. IEEE Transactions on Advanced Packaging, 2010, 33, 408-420.	1.6	13
25	Adaptive Fault Tolerance for Scalable Cluster Computing in Space. International Journal of High Performance Computing Applications, 2009, 23, 227-241.	3.7	5
26	Understanding Preferences for Recycling Electronic Waste in California. Environment and Behavior, 2009, 41, 101-124.	4.7	50
27	How much e-waste is there in US basements and attics? Results from a national survey. Journal of Environmental Management, 2009, 90, 3322-3331.	7.8	70
28	The Electronics Revolution: From E-Wonderland to E-Wasteland. Science, 2009, 326, 670-671.	12.6	209
29	Genetic Evolution for the Development of Robust Artificial Neural Network Logic Gates. , 2009, , .		0
30	Design and Evaluation of Bioepoxy-Flax Composites for Printed Circuit Boards. IEEE Transactions on Electronics Packaging Manufacturing, 2008, 31, 211-220.	1.4	34
31	Introspection-Based Fault Tolerance for COTS-Based High-Capability Computation in Space. , 2008, , .		1
32	Promoting Robust Design of Diode Lasers for Space: A National Initiative. Aerospace Conference Proceedings IEEE, 2008, , .	0.0	0
33	Moisture absorption phenomena in green composite printed circuit board prototypes. , 2008, , .		1
34	Genetic Programming of an Artificial Neural Network for Robust Control of a 2-D Path Following Robot. , 2008, , .		1
35	Reliability of semiconductor laser packaging in space applications. , 2008, , .		2
36	Engineering by Fundamental Elements of Evolution. , 2008, , .		1

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37	A Fast Technology Infusion Model for Aerospace Organizations. , 2007, , .		0
38	California households' willingness to pay for "green"™ electronics. Journal of Environmental Planning and Management, 2007, 50, 113-133.	4.5	65
39	Electronic Waste Recycling Preferences in California: The Role of Environmental Attitudes and Behaviors. Electronics and the Environment, IEEE International Symposium on, 2007, , .	0.0	5
40	Renewable-resource Printed Wiring Board Design using Natural Fibers and a Bio-based Thermosetting Matrix. Electronics and the Environment, IEEE International Symposium on, 2007, , .	0.0	3
41	Leaching Assessments of Hazardous Materials in Cellular Telephones. Environmental Science & Technology, 2007, 41, 2572-2578.	10.0	104
42	A Comparative Hierarchical Decision Framework on Toxics Use Reduction Effectiveness for Electronic and Electrical Industries. Environmental Science & Technology, 2007, 41, 373-379.	10.0	7
43	WIAD Minimization in Butterfly Laser Module Packages: Clip Design. IEEE Transactions on Advanced Packaging, 2007, 30, 499-505.	1.6	9
44	Chip-on-Board (CoB) technology for low temperature environments. Part I: Wire profile modeling in unencapsulated chips. Microelectronics Reliability, 2007, 47, 1246-1250.	1.7	5
45	Household Willingness to Recycle Electronic Waste. Environment and Behavior, 2006, 38, 183-208.	4.7	227
46	Semiconductor lasers beyond the fiber optics telecommunication wavelength. , 2005, , .		1
47	Adopting Lead-Free Electronics: Policy Differences and Knowledge Gaps. Journal of Industrial Ecology, 2004, 8, 59-85.	5.5	40
48	A comparison of microstrip models to low temperature co-fired ceramic's silver microstrip measurements. Microelectronics Journal, 2002, 33, 443-447.	2.0	12
49	Stress testing of a recrystallizing CaO-B2O3-SiO2 glass-ceramic with Ag electrodes for high frequency electronic packaging. Journal of Electronic Materials, 2001, 30, 386-390.	2.2	13